
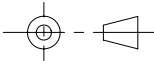


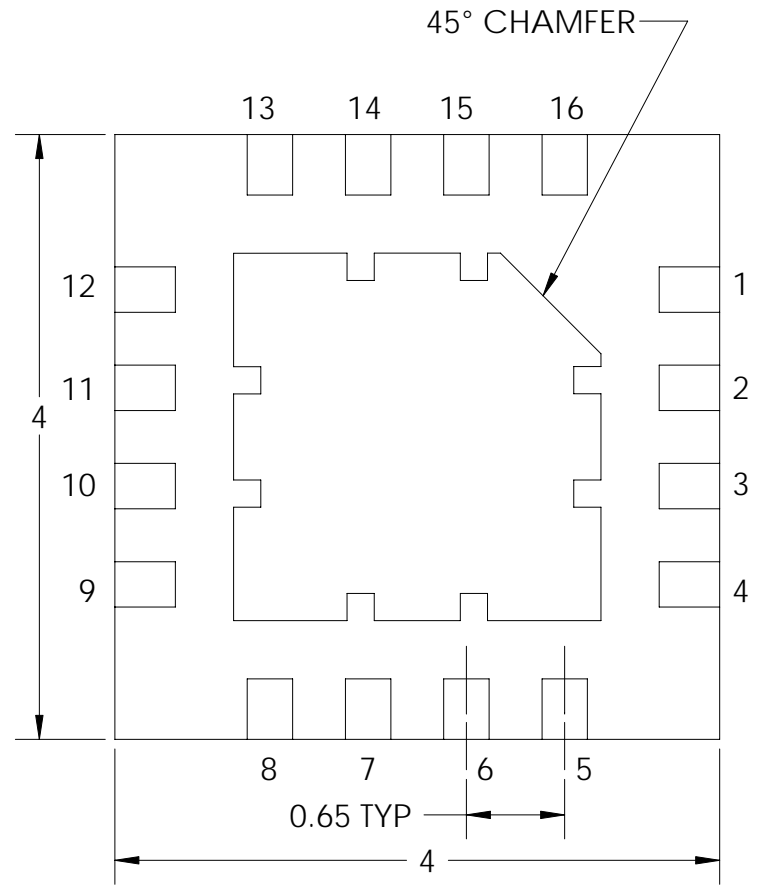
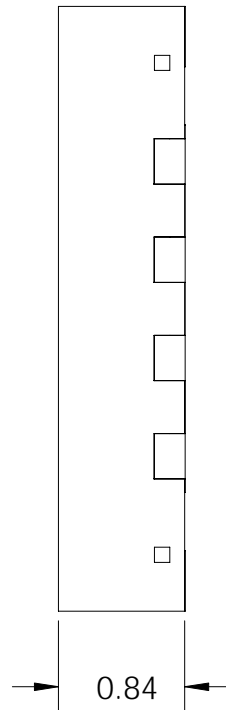
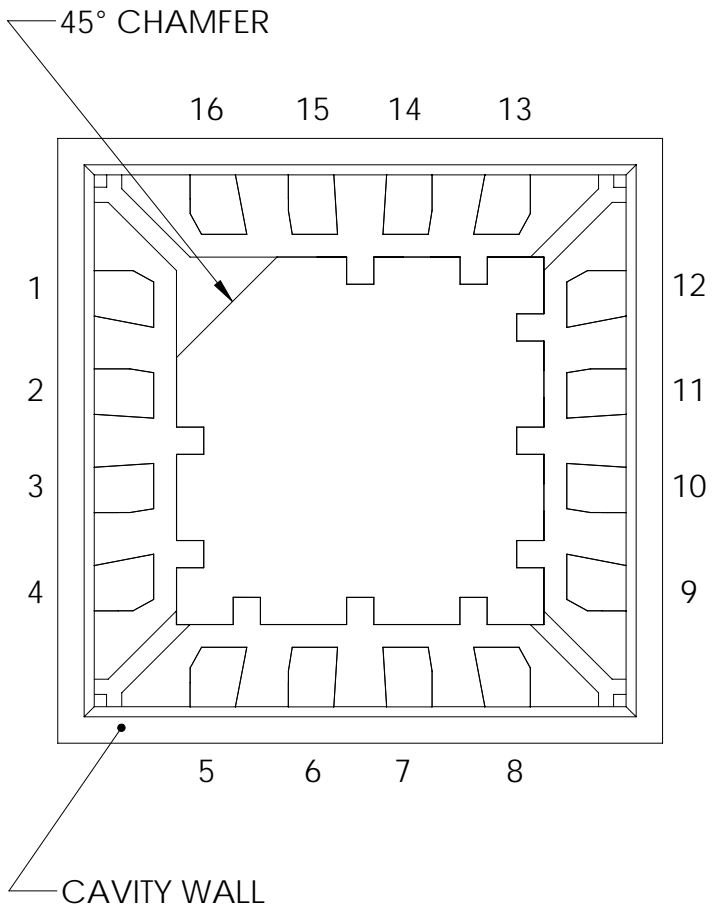
SECTION A-A  
SCALE 15 : 1

- Notes: (Unless Otherwise Specified)
- 1) BODY; PLASTIC, SEMICONDUCTOR GRADE
  - 2) LEAD FRAME: COPPER, C-194F/H
  - 3) LEAD FRAME PLATING: Ni, Pd, Au
  - 4) FRAME THICKNESS: 0.203mm
  - 5) DIE PAD: 2.4 X 2.4mm
  - 6) JEDEC OUTLINE: MO-220
  - 7) DIMENSIONS: mm

TOLERANCE UNLESS NOTED		APPROVALS		DATE	 <b>TITLE:</b> 16-LEAD 4mm P=0.65 mm M-QFN CAVITY PACKAGE			
X.X	± 0.05	DRAWN	MH	8/21/10				
X.XX	± 0.01	CHECKED						
X.XXX	± 0.005	ENG						
X.XXXX	± 0.0005	MFG						
ALL DIMENSIONS IN ☐ INCHES ☒ MILLIMETERS		Q.A.			SCALE	SIZE	DWG. NO.	REV
THIRD ANGLE PROJECTION		CUST			15:1	A	461650 M-QFN16W.65	A
		REVISED			DO NOT SCALE DRAWING		SHEET 1 OF 4	

TOP VIEW

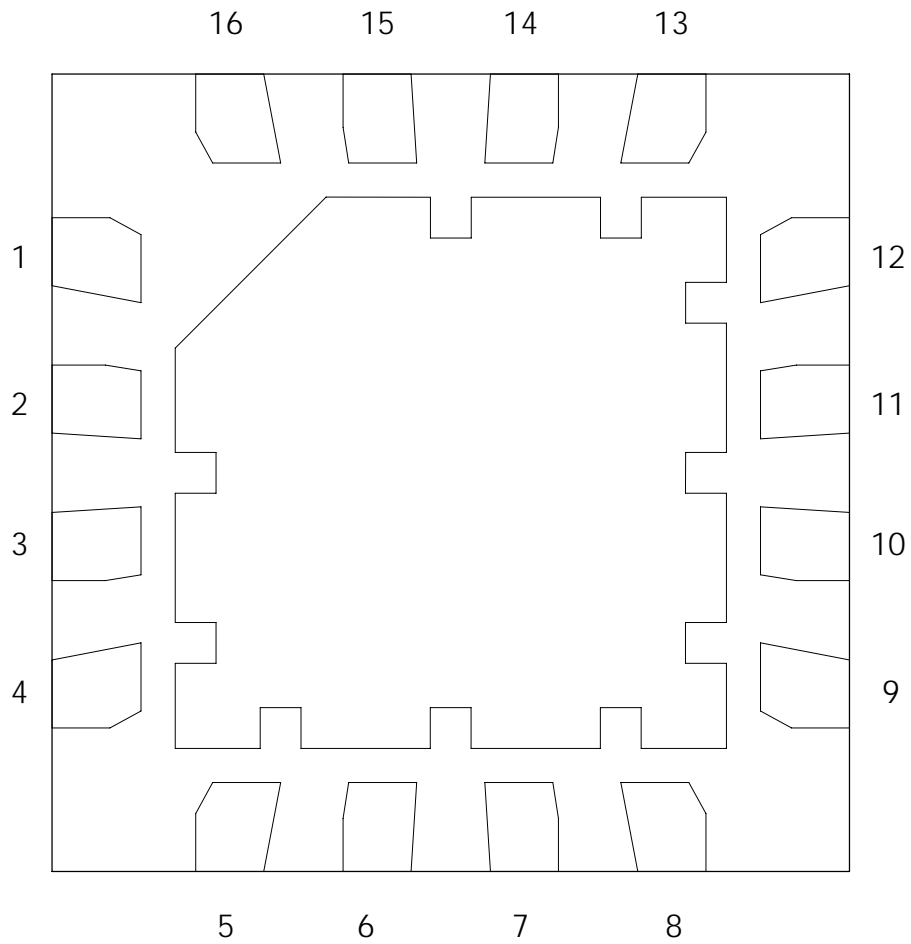
BOTTOM VIEW



TITLE:  
16-LEAD 4mm P=0.65 mm  
M-QFN CAVITY PACKAGE

SCALE	SIZE	DWG. NO.	REV
20:1	A	461650 M-QFN16W.65	A

# BONDING DIAGRAM



TITLE:

16-LEAD 4mm P=0.65 mm  
M-QFN CAVITY PACKAGE

SCALE  
**18:1**

SIZE  
**A**

DWG. NO.  
**461650**  
**M-QFN16W.65**

REV  
**A**

DO NOT SCALE DRAWING

SHEET 3 OF 4

